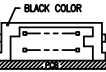


PRODUCT NO.

94898

PRODUCT NO.	STAND OFF	SOLDER TAIL	DIM "P" (mm)	DIM "Q" (mm)	FOR LOWER DECK OR UPPER DECK	③ HOLD DOWN	SHEET NO.	MOUNTING STYLE TO PCB		
94898-XXXX	DIM "M" (mm)									
000	0	R/A	2.8	—	LOWER	NONE	NO.2	TOP MOUNT 94898-0XXX		
000LF	0	R/A	2.8	—	LOWER	NONE				
000MLF	0	R/A	2.8	—	LOWER	NONE				
000H	0	R/A	2.8	—	LOWER	YES				
000HLF	0	R/A	2.8	—	LOWER	YES				
001	0	SMT STAGGERED	—	—	LOWER	NONE				
001LF	0	SMT STAGGERED	—	—	LOWER	NONE				
001H	0	SMT STAGGERED	—	—	LOWER	YES				
001HLF	0	SMT STAGGERED	—	—	LOWER	YES				
002	0	SMT IN LINE	—	—	LOWER	NONE				
002LF	0	SMT IN LINE	—	—	LOWER	NONE	NO.3			
002H	0	SMT IN LINE	—	—	LOWER	YES				
002HLF	0	SMT IN LINE	—	—	LOWER	YES				
010	4	R/A	2.8	—	LOWER	NONE				
010LF	4	R/A	2.8	—	LOWER	NONE				
020	5	R/A	2.8	—	LOWER	NONE				
020LF	5	R/A	2.8	—	LOWER	NONE				
020MLF	5	R/A	2.8	—	LOWER	NONE				
021MLF	5	R/A	2.8	—	LOWER	NONE				
040	2	R/A	2.5	—	LOWER	NONE			NO.4	
040MLF	2	R/A	2.5	—	LOWER	NONE				
040LF	2	R/A	2.5	—	LOWER	NONE				
005	FDR 0	R/A	2.8	8.6	UPPER	NONE				
005LF	FDR 0	R/A	2.8	8.6	UPPER	NONE				
045	FDR 2	R/A	2.5	10.3	UPPER	NONE				
045MLF	FDR 2	R/A	2.5	10.3	UPPER	NONE				
045LF	FDR 2	R/A	2.5	10.3	UPPER	NONE				
500	0	R/A	2.8	—	LOWER	NONE	NO.5	BOTTOM MOUNT 94898-5XXX		
500LF	0	R/A	2.8	—	LOWER	NONE				
500H	0	R/A	2.8	—	LOWER	YES				
500HLF	0	R/A	2.8	—	LOWER	YES				
501	0	SMT STAGGERED	—	—	LOWER	NONE				
501LF	0	SMT STAGGERED	—	—	LOWER	NONE				
501H	0	SMT STAGGERED	—	—	LOWER	YES				
501HLF	0	SMT STAGGERED	—	—	LOWER	YES				
502	0	SMT IN LINE	—	—	LOWER	NONE				
502J	0	SMT IN LINE	—	—	LOWER	NONE			NO.6	
502LF	0	SMT IN LINE	—	—	LOWER	NONE				
502H	0	SMT IN LINE	—	—	LOWER	YES				
502HLF	0	SMT IN LINE	—	—	LOWER	YES				
510	4	R/A	2.8	—	LOWER	NONE				
510LF	4	R/A	2.8	—	LOWER	NONE				
520	5	R/A	2.8	—	LOWER	NONE				
520LF	5	R/A	2.8	—	LOWER	NONE				
530	2	R/A	1.48	—	LOWER	NONE				
530LF	2	R/A	1.48	—	LOWER	NONE	NO.7			
540	2	R/A	2.5	—	LOWER	NONE				
540LF	2	R/A	2.5	—	LOWER	NONE				
505	FDR 0	R/A	2.8	8.6	UPPER	NONE				
505LF	FDR 0	R/A	2.8	8.6	UPPER	NONE				
535	FDR 2	R/A	1.48	9.28	UPPER	NONE				
535LF	FDR 2	R/A	1.48	9.28	UPPER	NONE				
545	FDR 2	R/A	2.5	10.3	UPPER	NONE				
545LF	FDR 2	R/A	2.5	10.3	UPPER	NONE				

NOTES

1. PRODUCT SPEC:110-263

94898-X X X X X X

OPTIONAL LEED FREE

NONE : N 0

LF : YES

OPTIONAL HOLD DOWN

NONE : N 0

H : YES (SEE FIGURE OF -xxxH)

LOW COST VERSION

NONE : N 0

M : YES (DETAIL AS COMPONENT)

SOLDER TAIL

0 : R/A

(FOR LOWER & SINGLE)

1 : SMT STAGGERED (FOR LOWER ONLY)

2 : SMT IN LINE (FOR LOWER ONLY)

5 : R/A (FOR UPPER ONLY)

STAND OFF

0 : 0mm

1 : 4mm

2 : 5mm

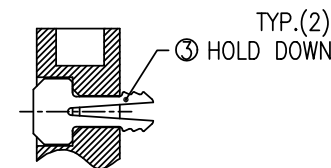
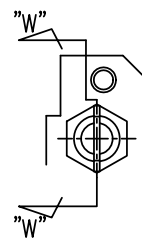
3 : 2mm (SPECIAL TAIL LENGTH)

4 : 2mm

MOUNTING STYLE

0 : TOP MOUNTING

5 : BOTTOM MOUNTING



SECTION "W"-"W"

94898-xxxH
(OPTIONAL HOLD DOWN)

mat'l. code				surface		tolerance		projection	product family			
				ISO 1302		ISO 406 ISO 1101		MM	PCMCIA			
l	tr	ec	n	dr	date	tolerances unless otherwise specified		linear	title			
J	N06-0065	M.Z			04/02/06	0.X±0.3		MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE			
K	N07-0219	M.Z			12/07/07	0.XX±0.13						
L	N08-0041	M.Z			03/10/08	±2'		scale 1:1				
M	N08-0219	M.Z			10/10/08	dr M.Hasegawa 2/24/05			dwg no			
N	N09-0045	SH			05/25/09	engr M.Hasegawa 2/24/05			sheet 1 of 7			
P	ELX-N-007954	ZK			11/01/11	chr			94898			
				appd					type CUSTOMER			
sheet				revision		P	P	P	P	P	P	P
index				sheet		1	2	3	4	5	6	7

PDS: Rev :P

STATUS: Released

Printed: Dec 19, 2011

PRODUCT NO.

94898-000

94898-000LF

94898-000H

94898-000HLF

94898-000MLF

94898-001

94898-001LF

94898-001H

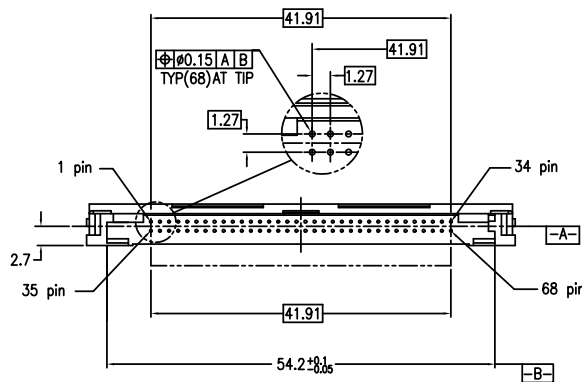
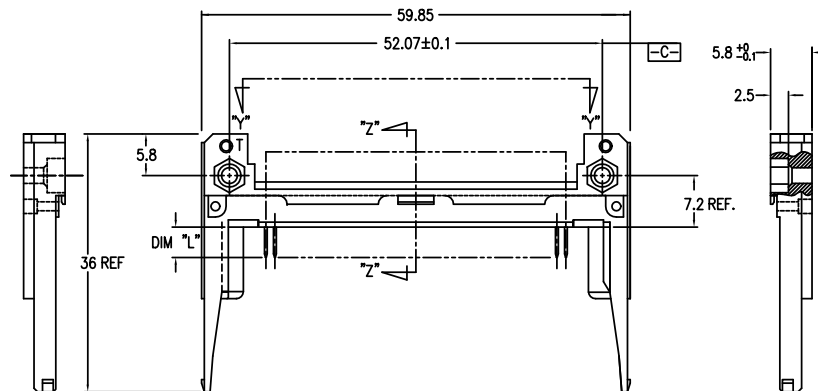
94898-001HLF

94898-002

94898-002LF

94898-002H

94898-002HLF

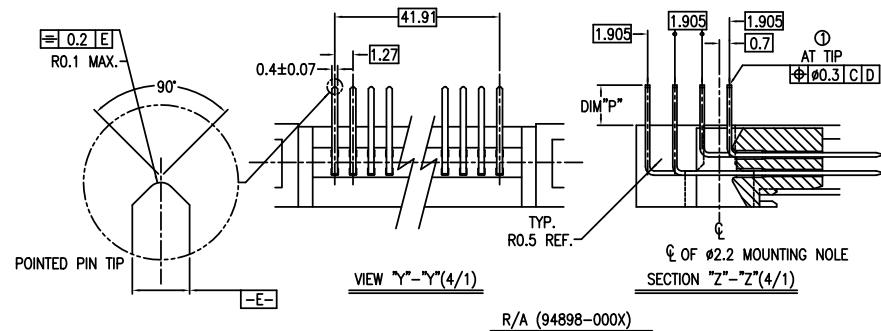


NOTES

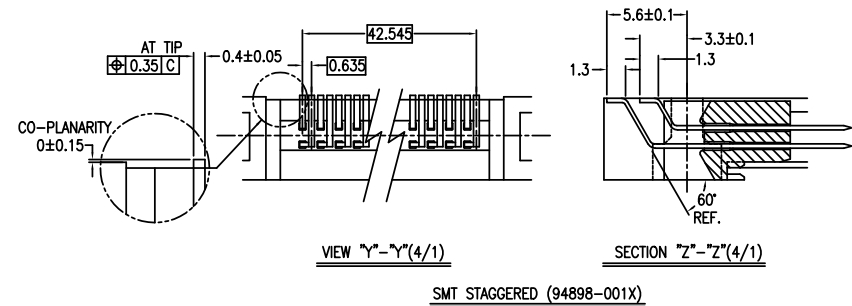
- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni.
CONTACT AREA : 0.1µm MIN. Au.
OVER 0.5µm MIN. Pd-Ni.
SOLDER AREA : 2.5µm MIN. Sn-Pb.
OR 2.5µm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5µm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

	DIM "L"		
PIN No.	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS		36.67	1.1734 35.5168

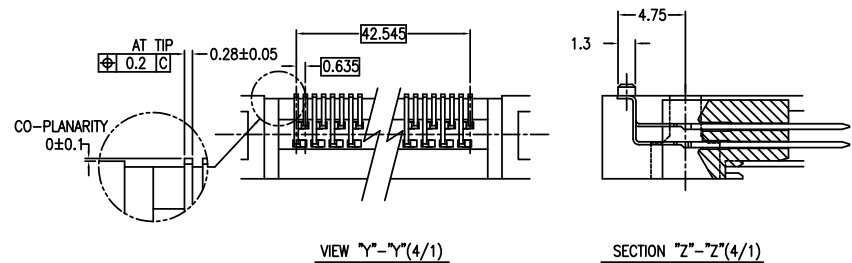
- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION



R/A (94898-000X)



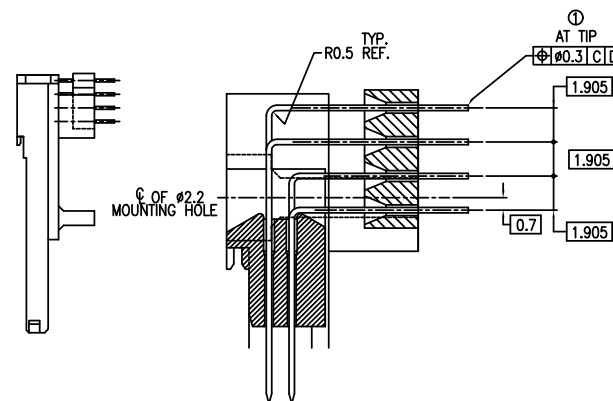
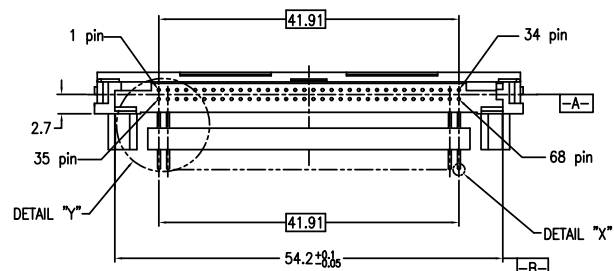
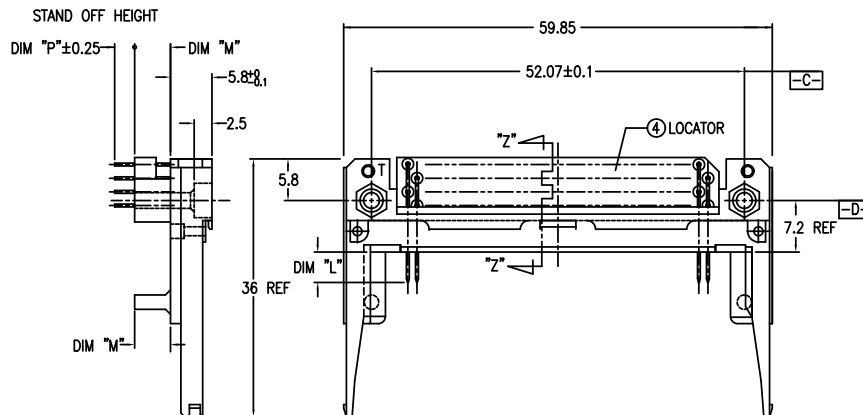
SMT STAGGERED (94898-001X)



SMT IN LINE (94898-002X)

mat'l. code		surface	tolerance	projection	product family
		ISO 1302	ISO 406 ISO 1101	ISO 1101	PCMCIA
l'tecn nldr date		tolerances unless otherwise specified			title
P		angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
		linear	0.XX±0.13		
		±2'	0.XXX±0.05	scale 1:1	
		dr	M.Hasegawa 2/24/05		dwg no
		engr	M.Hasegawa 2/24/05		94898
		chr			sheet 2 of 7
		appd			size
sheet	revision				type CUSTOMER Drawing
index	sheet				

PRODUCT NO.
94898-010
94898-010LF
94898-020/020M
94898-020LF/020MLF
94898-021MLF
94898-040
94898-040LF/040MLF

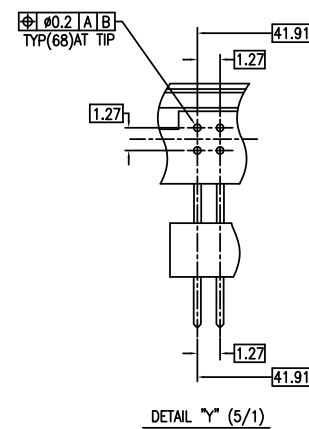


SECTION "Z"- "Z" (5/1)

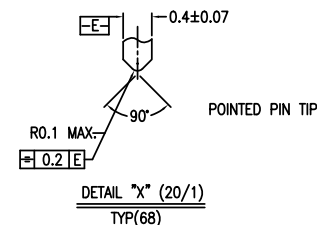
- ① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
④ FINISH
PIN
UNDER PLATING : 0.5um MIN. Ni.
CONTACT AREA : 0.1um MIN. Au.
OVER 0.5um MIN. Pd-Ni.
SOLDER AREA : 2.5um MIN. Sn-Pb.
OR 2.5um MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5um MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
6. SEQUENCE PIN ASSIGNMENT

PIN No.	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	1.17.34	35.51.88

7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12 "M" SHOWS IT IS LOW COST VERSION, IT IS OPTIONAL AND IN FIRST OF LETTER OF PART NO., SUCH AS 94898-020MLF IS LOW COST VERSION 94898-020LF IS NOT LOW COST VERSION.



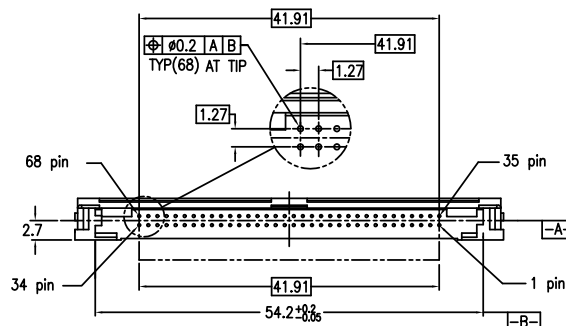
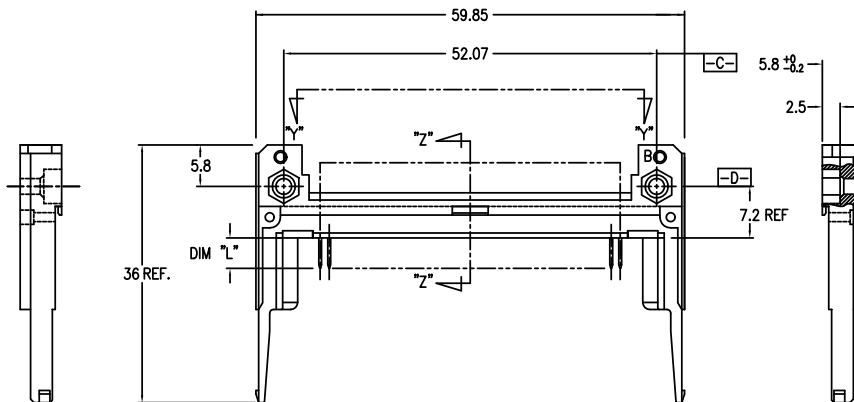
DETAIL "Y" (5/1)

DETAIL "X" (20/1)
TYP(68)

mat'l. code		surface		tolerance		projection		product family	
ISO 1302		ISO 406		ISO 1101		ISO 1101		PCMCIA	
l'tecn nodr date		tolerances unless otherwise specified		title		scale 1:1		68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE	
P		angles		linear		MM		dwg no 94898	
		±2'		0.X±0.3		0.XX±0.13		sheet 3 of 7	
		dr M.Hasegawa 2/24/05		0.XXX±0.05		scale 1:1		size A4	
		engr M.Hasegawa 2/24/05							
		chr							
		appd							
sheet index		revision sheet						type CUSTOMER Drawing	

PRODUCT NO.
94898-500
94898-500LF
94898-500H
94898-500HLF
94898-501
94898-501LF
94898-501H
94898-501HLF
94898-502
94898-502J
94898-502LF
94898-502H
94898-502HLF

-SEE NOTE 12



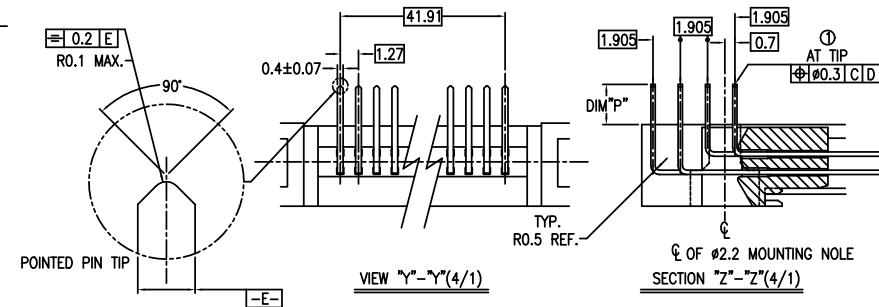
NOTES

1. TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
2. SEE TA-946 FOR PCB LAYOUT.
3. MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
4. FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni.
CONTACT AREA : 0.1μm MIN. Au.
OVER 0.5μm MIN. Pd-Ni.
SOLDER AREA : 2.5μm MIN. Sn-Pb.
OR 2.5μm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5μm MIN. PURE Sn.
5. RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1

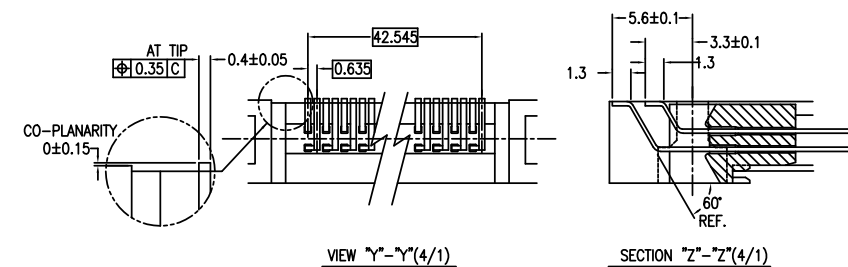
6. SEQUENCE PIN ASSIGNMENT

PIN No.	OTHERS	DIM "L"	
		4.25±0.1	5.0±0.1
		36.67	36.51

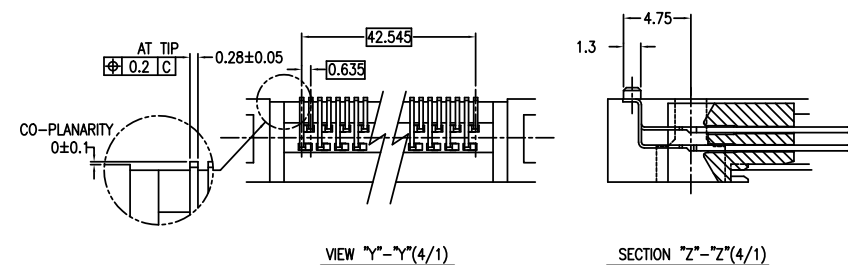
7. GENERAL TOLERANCE : ±0.3
8. SEE SHEET 1 REGARDING COMPONENTS.
9. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
10. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
11. IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION
12. THE P/N 94898-502J HAS SPECIAL TRAY, IT IS 10084720-001.



R/A (94898-500X)



SMT STAGGERED (94898-501X)



SMT IN LINE (94898-502X)

mat'l. code				surface	tolerance	projection	product family
ISO 1302				ISO 406	ISO 1101	MM	PCMCIA
date				tolerances unless otherwise specified			
P				angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
				linear	0.XX±0.13	scale 1:1	
				±2'	0.XXX±0.05		
				dr	M.Hasegawa	2/24/05	dwg no
				engr	M.Hasegawa	2/24/05	sheet 5 of 7
				chr			size
				appd			A4
sheet	revision						type
index	sheet						CUSTOMER Drawing

①
AT TIP
Ø0.3 C/D

TYP.
R0.5 REF.

1.905

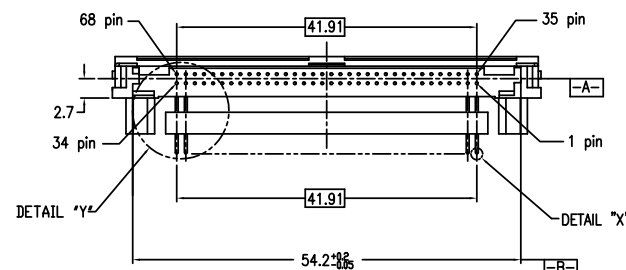
1.905

0.7

1.905

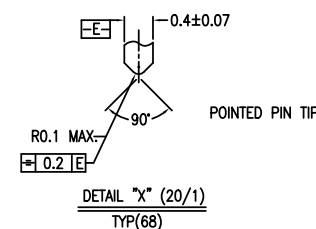
C OF Ø2.2
MOUNTING HOLE

SECTION "Z"- "Z" (5/1)

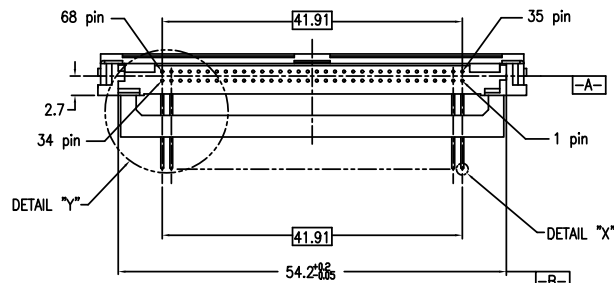
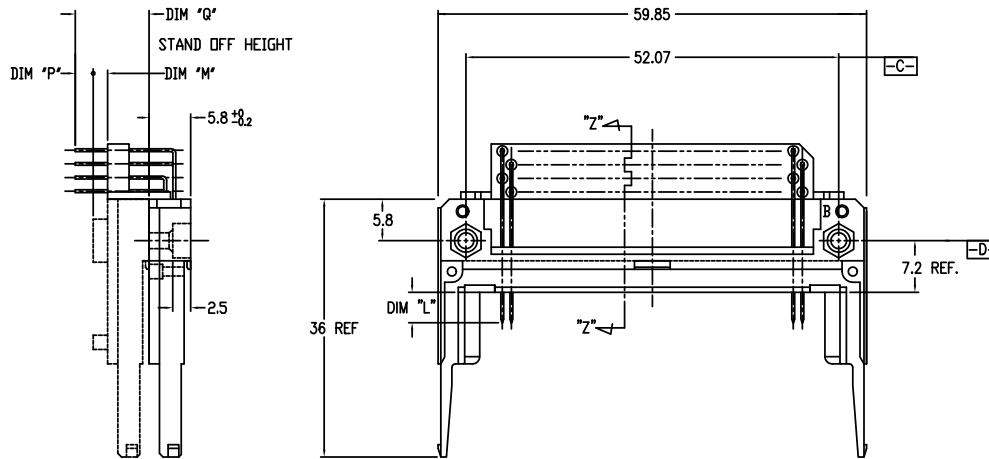


	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1.17 ³⁴ 35.51 ⁶⁸

Technical drawing of a detail of a Y-shaped structure, labeled "DETAIL 'Y' (5/1)". The drawing shows a cross-section of a Y-shaped component with a central vertical stem and two side arms. The top of the side arms are rounded. Dimensions are indicated: a diameter of 41.9 mm for the top of the side arms, a diameter of 41.9 mm for the bottom of the central stem, a diameter of 1.27 mm for the central stem, and a diameter of 1.27 mm for the side arms. A note at the top left indicates a tolerance of 0.2 mm for the diameter of the side arms, with a typical tolerance of 0.08 mm at the tip. A section line A-B is shown across the top of the side arms.

Printed: Dec 19, 2011

PRODUCT NO.
94898-505
94898-505LF
94898-535
94898-535LF
94898-545
94898-545LF

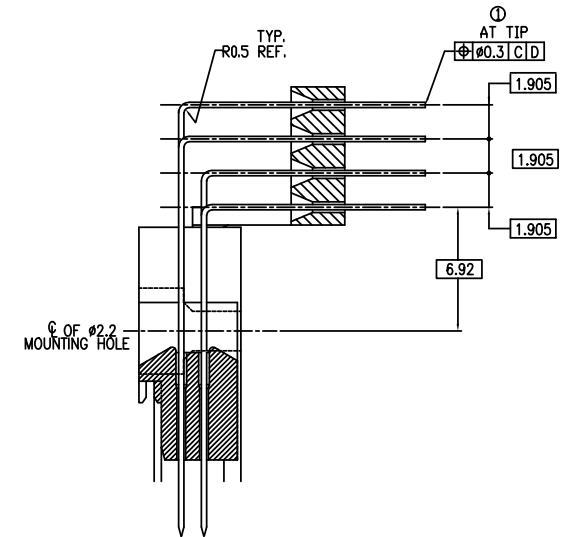
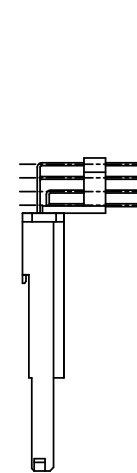


NOTES

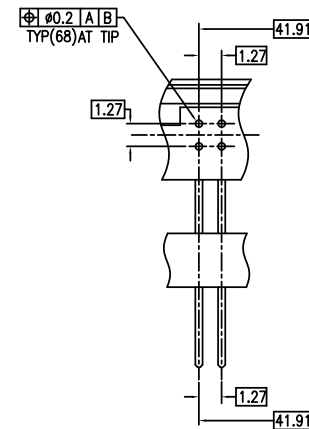
- TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
- SEE TA-946 FOR PCB LAYOUT.
- MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC
PIN : COPPER ALLOY.
HOLD-DOWN : BRASS
- FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni.
CONTACT AREA : 0.1μm MIN. Au.
OVER 0.5μm MIN. Pd-Ni.
SOLDER AREA : 2.5μm MIN. Sn-Pb.
OR 2.5μm MIN. PURE Sn.(FOR -XXXLF)
HOLD-DOWN : 2.5μm MIN. PURE Sn.
- RECOMMENDED PCB HOLE (OPTIONAL HOLD-DOWN) : 2.3±0.1
- SEQUENCE PIN ASSIGNMENT

PIN No.	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	17.54	35.51±0.6

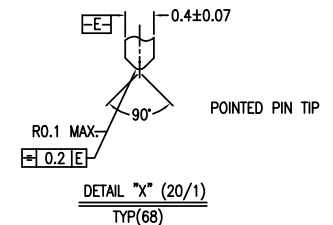
- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.
- IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- IF LEAD FREE P/N, PACKAGE MEETS GS-14-920 SPECIFICATION



SECTION "Z"- "Z" (5/1)



DETAIL "Y" (5/1)

DETAIL "X" (20/1)
TYP(68)

mat'l. code		surface	tolerance	projection	product family
		ISO 1302	ISO 406 ISO 1101		PCMCIA
l	tr	ec	n	o	d
date		tolerances unless otherwise specified			title
P		angles	0.X±0.3	MM	68 POS EJECTOR HEADER ASSY FOR LOW VOLTAGE
		linear	0.XX±0.13	scale 1:1	
		±2°	0.XXX±0.05		
		dr	M.Hasegawa 2/24/05		dwg no
		eng	M.Hasegawa 2/24/05		sheet 7 of 7
		chr			size
		app			A4
sheet	revision				type CUSTOMER Drawing
index	sheet				